

Polysaccharide Modified Joint Compound

DESCRIPTION

Technical Evaluation of a Joint Compound using a Polysaccharide Modified Binder

ADVANTAGES

- Excellent adhesion to wall board and tape
- Superior workability and open time for spackle
- Spreads quickly for application
- Taping and topping can be done with a single compound
- Outstanding sanding characteristics
- Cost competitive
- Replacing traditional latex emulsion binders with Lorama Polysaccharide Resin Technology (LPRT) - LTB® enhances application, provides superior adhesion to reinforcing tape, and improves sanding characteristics

USAGE GUIDE

Due to the wide variety of substrates, surface preparation and application methods, customers should test the complete system for adhesion and compatibility prior to full-scale application, taking environmental conditions into consideration.

Substrate should be free of grease, oil, dirt, sand or other loose materials and debris. Apply the compound evenly, allowing each coat to dry before sanding for a smooth finish.

TYPICAL PROPERTIES

Values below are not specifications:

FORMULATION PHYSICALS	
LTB® Binder Replacement (%)	30
Viscosity (Poise)	1500
Shrinkage (%)	18-20

TAPE AND DRYWALL ADHESION TEST



Control

LTB® Modified

Please visit our website www.loramabiocoatings.com or contact us at lppt@lorama.com

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